

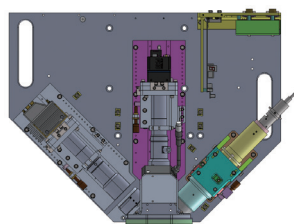
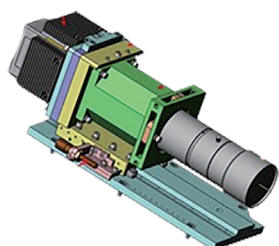


超高速・高精度検査  
High-Throughput & Accuracy

2D/3D同時測定システム  
Simultaneous 2D/3D measuring system

バンプ径/ピッチ微細化対応  
Compatible with finer bump diameter/pitch

お客様の用途に合わせ多彩なラインアップ  
Diverse lineup to suit needs

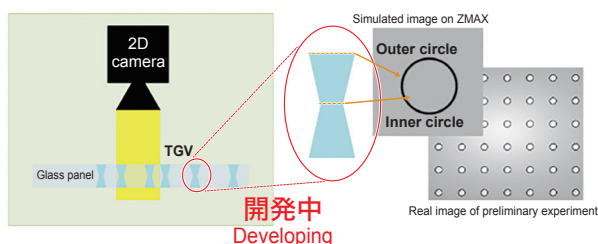


三角測量法  
Laser Triangulation

|                         | RSH-4                                                                                                                                                 | RSH-12 | RSH-23                                                                                                                                                  | RSH-50            |
|-------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------|--------|---------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------|
| FOV (μm)                | 4                                                                                                                                                     | 12     | 23                                                                                                                                                      | 50                |
| Minimum bump size (μm)  | 10                                                                                                                                                    | 45     | 50                                                                                                                                                      | 開発中<br>Developing |
| Minimum bump pitch (μm) | 20                                                                                                                                                    | 90     | 100                                                                                                                                                     |                   |
| 3D Resolution (μm)      | 1.3                                                                                                                                                   | 5      | 10                                                                                                                                                      |                   |
| 2D Resolution (μm)      | 0.91                                                                                                                                                  | 2.39   | 5.48                                                                                                                                                    |                   |
| Type of bumps           | <ul style="list-style-type: none"> <li>• Flip Chip flat/round bump,</li> <li>• Flip Chip top area/diameter,</li> <li>• CSP flat/round bump</li> </ul> |        | <ul style="list-style-type: none"> <li>• Warpage inspection</li> <li>• SOP inspection</li> <li>• Passive component inspection</li> <li>• BGA</li> </ul> |                   |

※上記の仕様外でもご相談ください。他のラインアップを取り揃えています。  
Please contact us even if it is outside the specifications. We have other lineups.

開発中 | Developing



開発中  
Developing

ガラスインターポーザーのTGV形状を検査  
TGV shape inspection

